

ECR	ECR NUMBER	DATE
	-----	xx/xx/xx

NOTES:

1. PLACE NET NAMES ON ALL JUMPERS AND HEADERS.
2. PLACE ALL PARTS OTHER THAN SMA CONNECTORS ON A 0 OR 90 DEGREE ORIENTATION.
3. SERIAL DATA SHOULD BE ROUTED AS 100 OHM DIFFERENTIALLY COUPLED OR SINGLE-ENDED 75 OHM TRANSMISSION LINES ON OUTSIDE LAYERS. ROUTING DISTANCE SHOULD BE 5 INCHES OR LESS. ALL OTHER DATA LINES SHOULD BE 50 OHM IMPEDIANCE ON INTERNAL OR EXTERNAL LAYERS. ROUTED POWER SHOULD BE A MINIMUM OF 40 MILS WIDE.
4. USE FR4-370 MATERIAL FOR ALL LAYERS.
5. SERIAL and REFCLK NETS MUST MATCH WITHIN +/- 0.5 MILS
6. MATCH DIFFERENTIAL TRACE WIDTHS OF SERIAL DATA LINES.
7. PLACE TI LOGO, BOARD NAME, JN COMBO LOGO, AND THE BOARD NUMBER IN TOP SIDE METAL.

### SCHMATIC SHEET INDEX:

- SHEET 01: TLK10xxx HD-SDI MOTHER BOARD COVER SHEET AND NOTES
- SHEET 02: LS INPUTS / OUTPUTS
- SHEET 03: CAMERA INPUT 1
- SHEET 04: CAMERA INPUT 2
- SHEET 05: CAMERA INPUT 3
- SHEET 06: CAMERA INPUT 4
- SHEET 07: OUTPUT SIGNALS MONITOR 1 / MONITOR 2
- SHEET 08: OUTPUT SIGNALS MONITOR 3 / MONITOR 4
- SHEET 09: COMMON SIGNALS
- SHEET 10: POWER



### TEXAS INSTRUMENTS

SCHEMATIC TITLE  
TIDA-00352  
TLK10xxx HD-SDI MOTHER BOARD

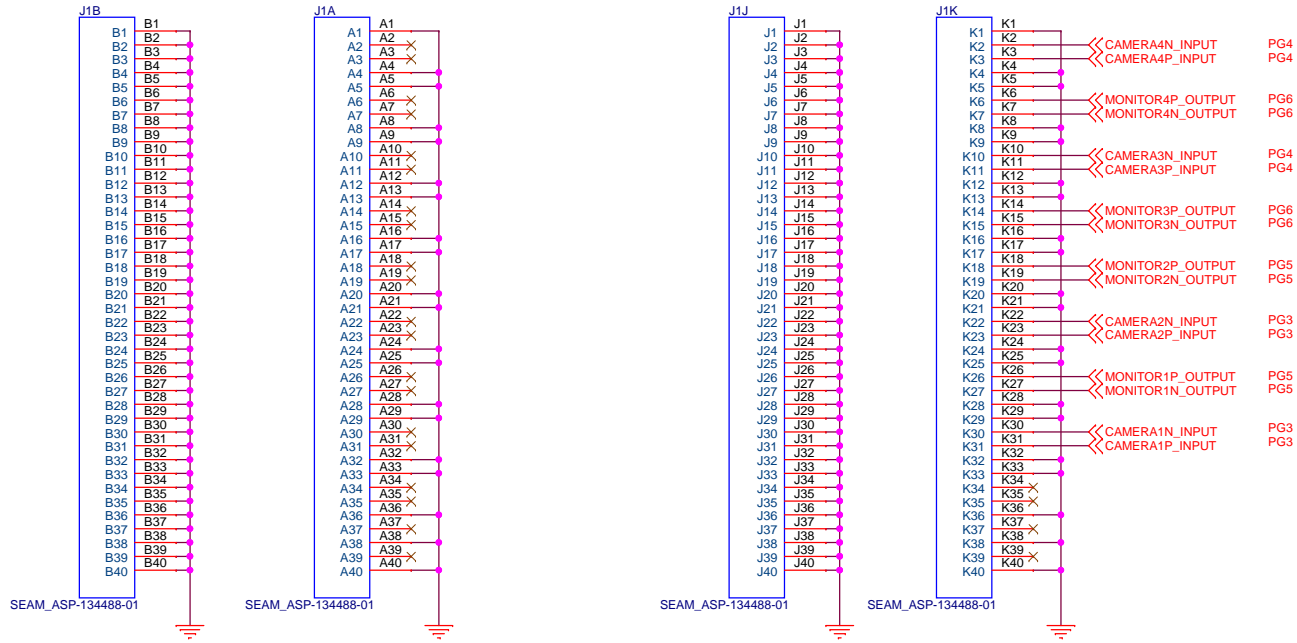
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LAYOUT	DATE
DFW TEST	08/15/14
RELEASED	DATE
M. PEFFERS	08/15/14

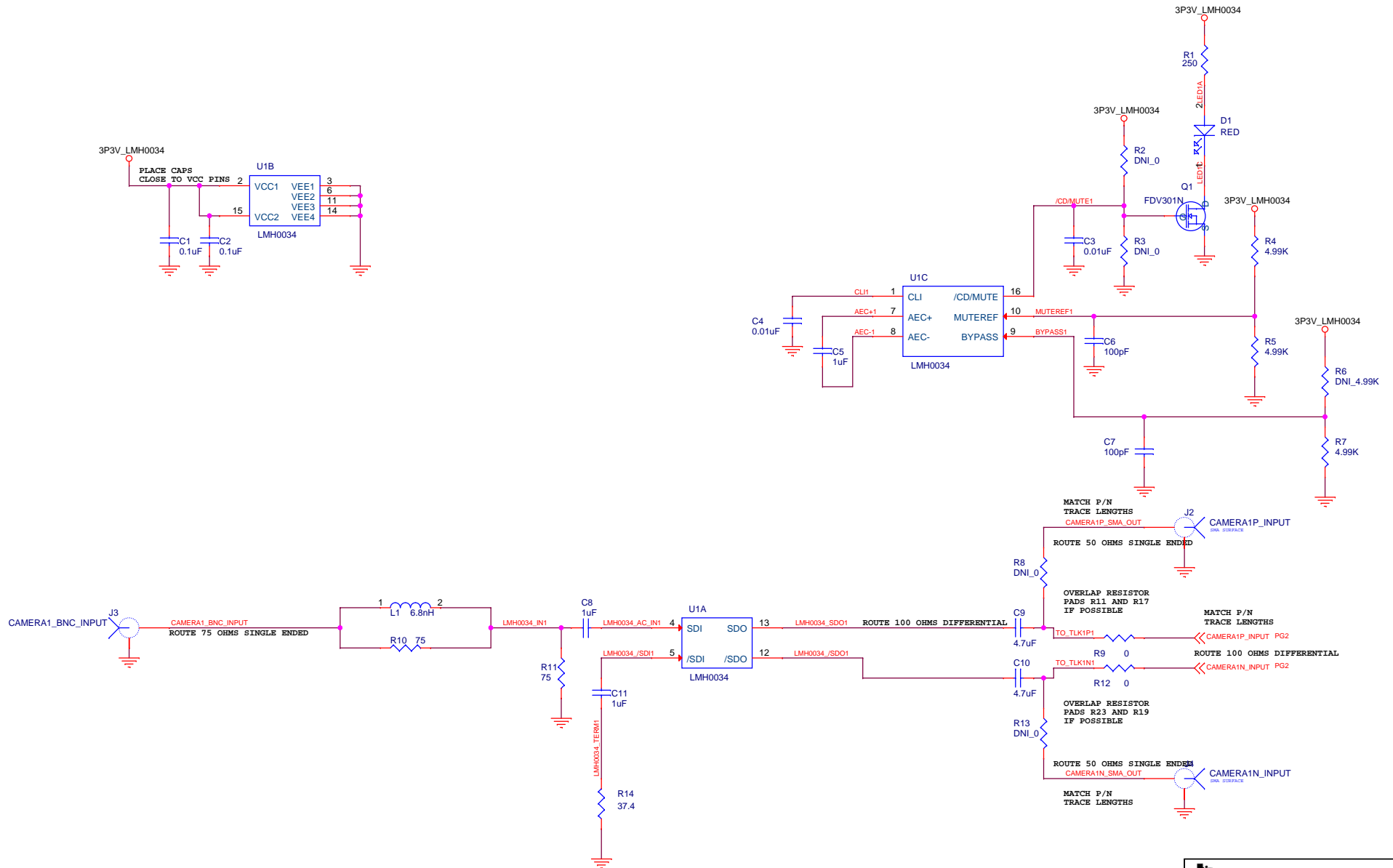
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COVER PAGE AND NOTES

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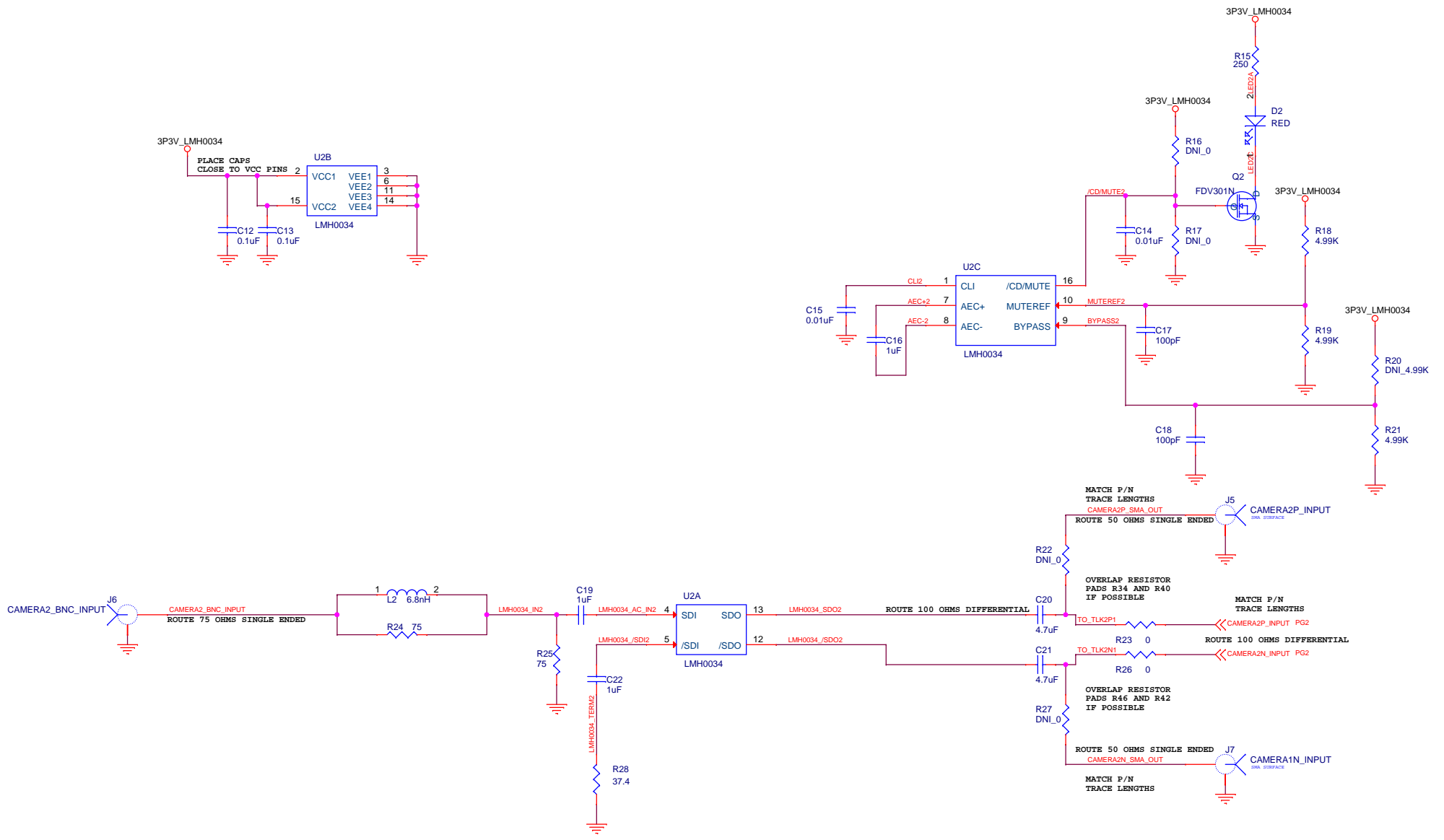
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DATA SHEET LAST UPDATED ON: xx/xx/xx

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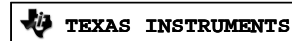
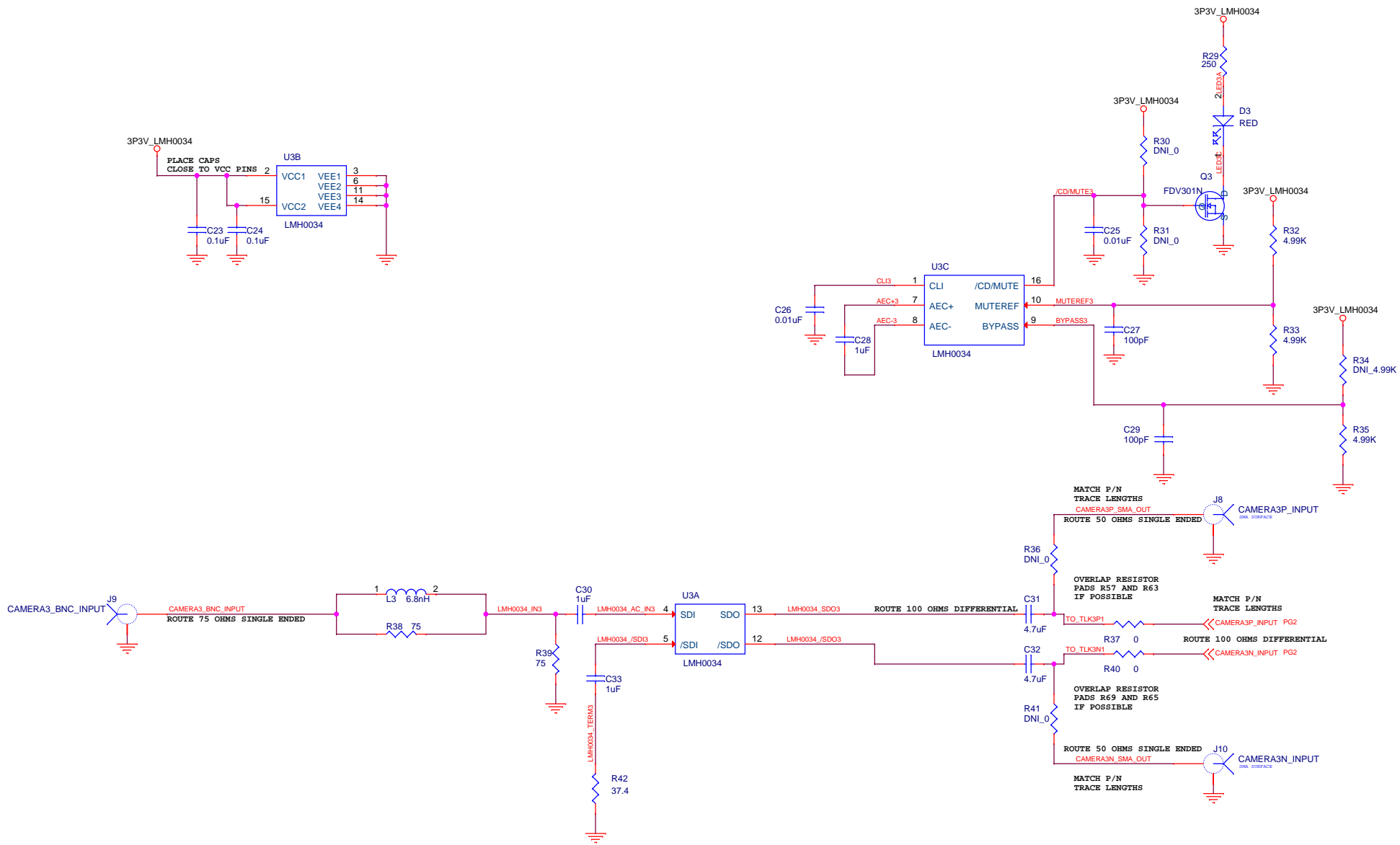


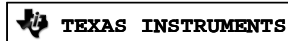
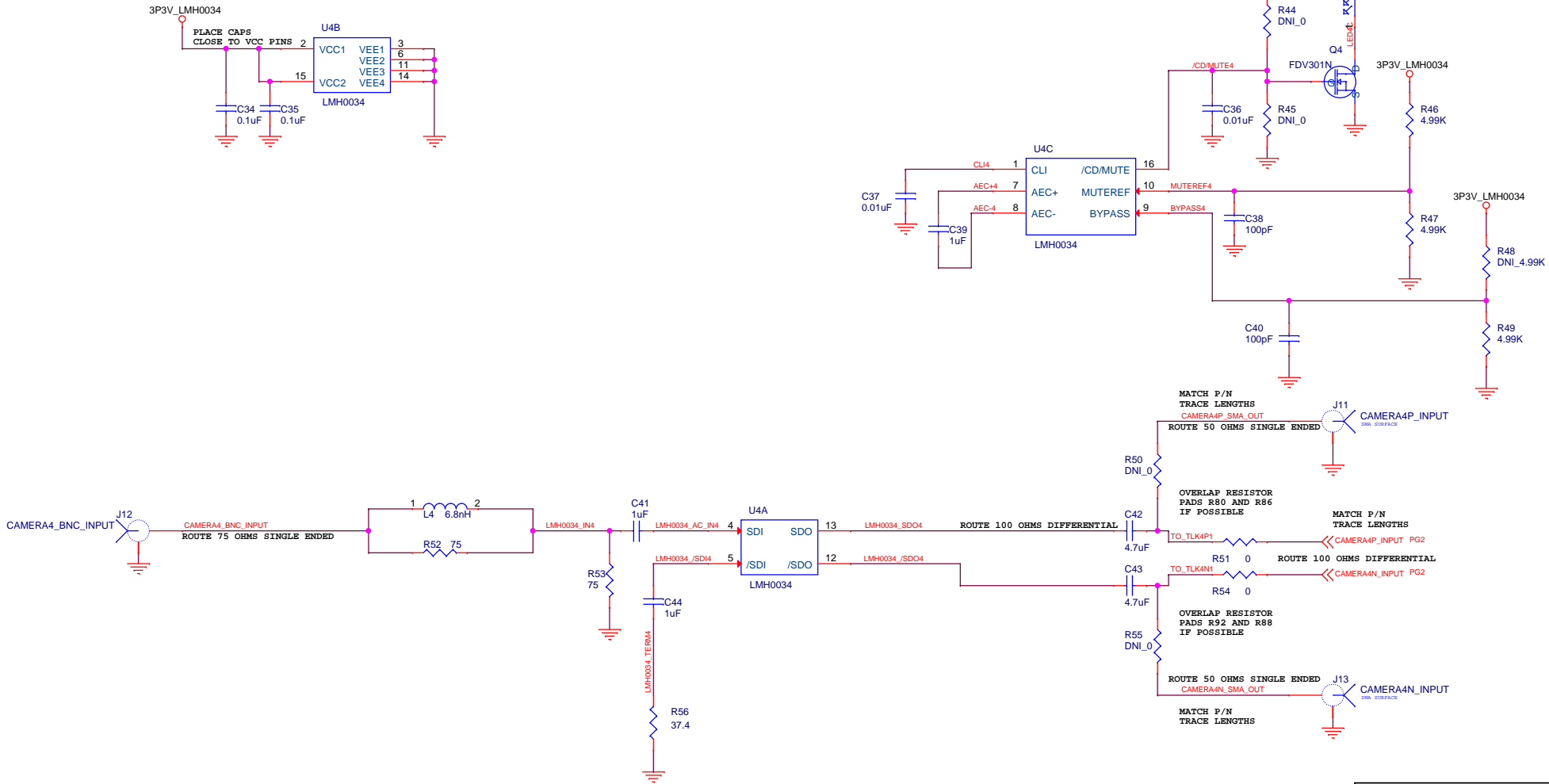


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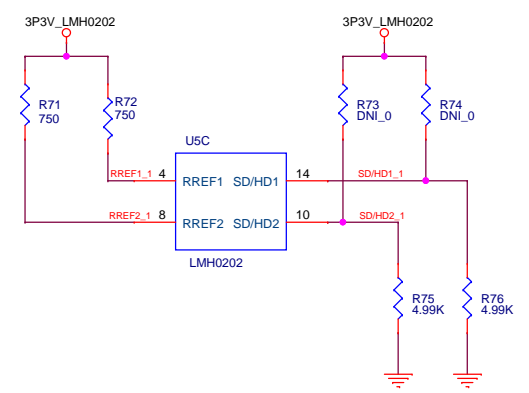
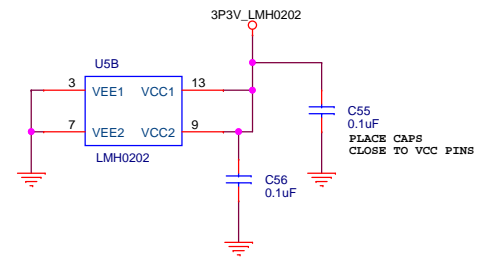
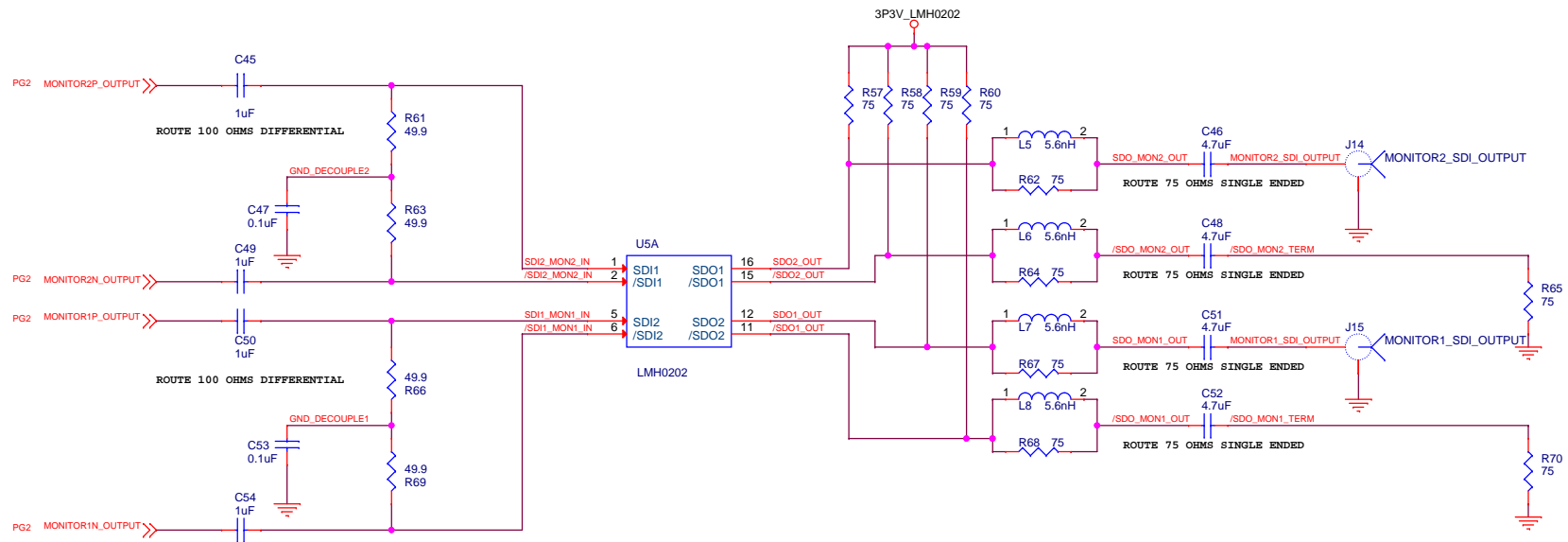


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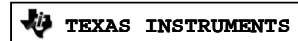
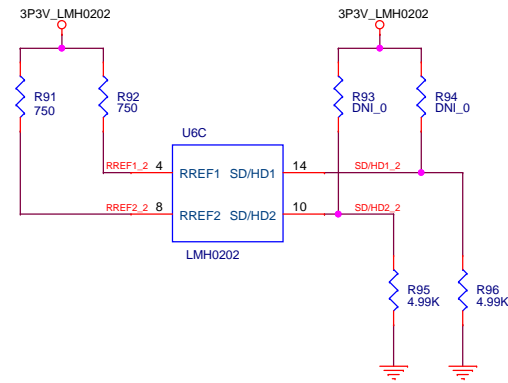
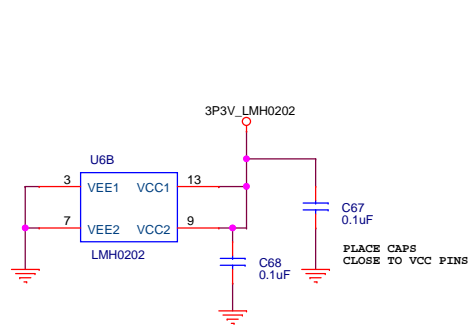
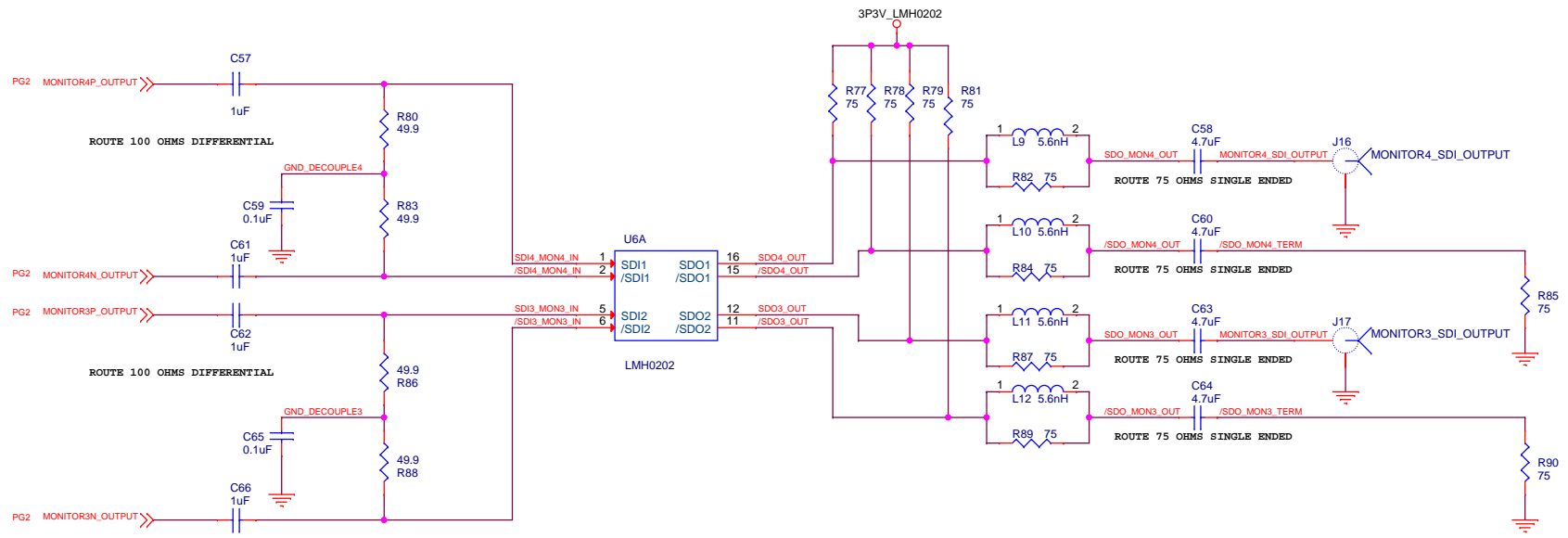




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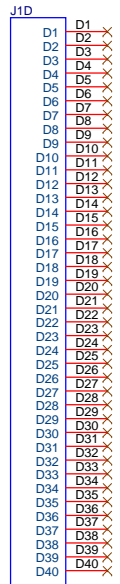


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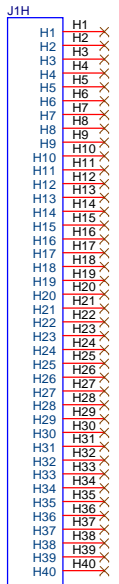


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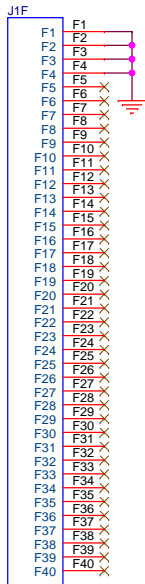




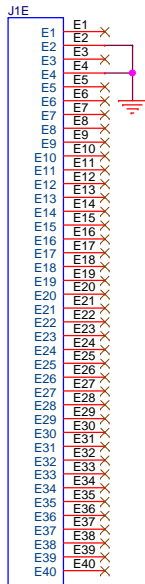
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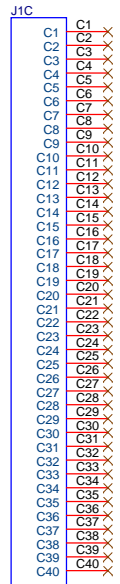
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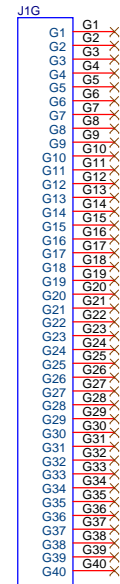
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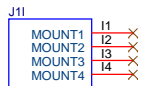
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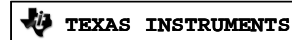
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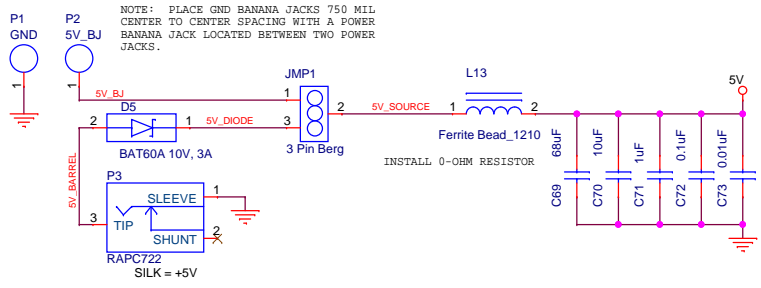
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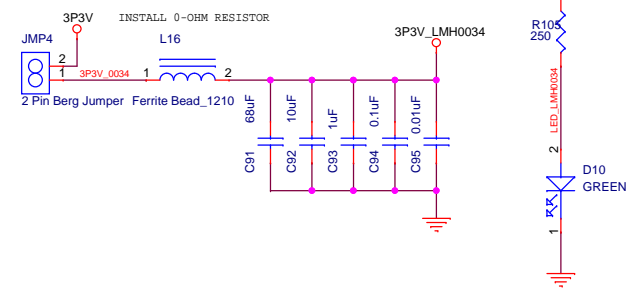
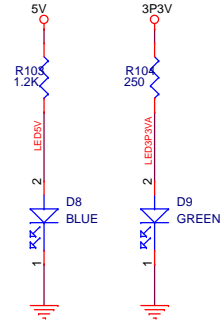
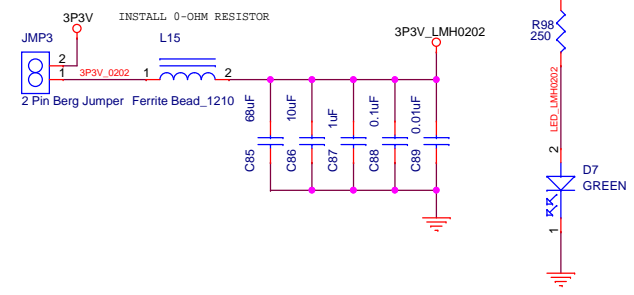
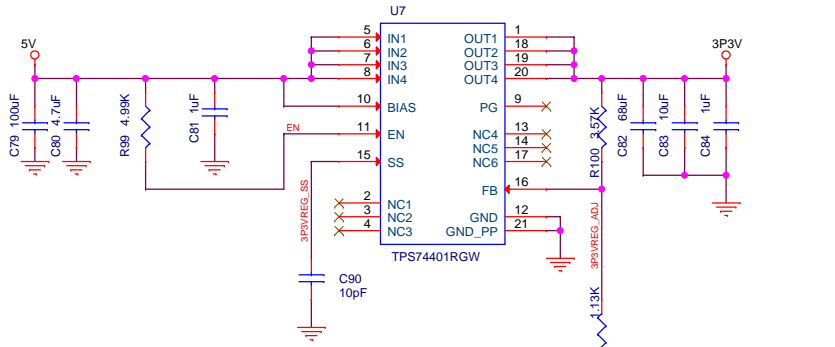
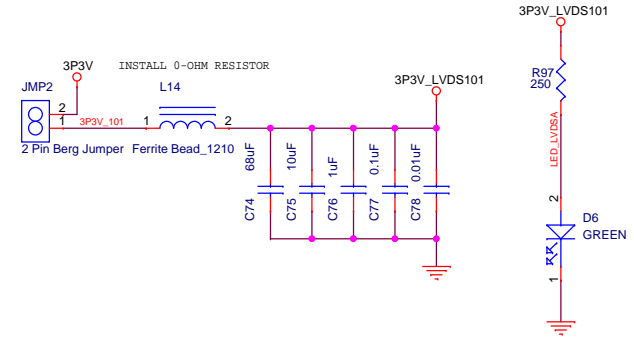
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1

# DAUGHTER CARD POWER



# INPUT BUFFER POWER



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